

CY2961

Pentium® and Cyrix® Compatible Clock Synthesizer/Driver with SDRAM Support

Features

- Pin for pin replacement for the ICW48C61-01, ICS9169C-23, and PLL52C61-01 (-1 Option)
- · Complete clock solution to meet requirements of Pentium® or Cyrix® motherboards with SDRAM support
 - Eight CPU clocks up to 83.3 MHz (see Function Table)
 - Six PCI clocks, synchronous or asynchronous mode, pin-selectable by Bus Select input
 - One USB clock at 48 MHz
 - One I/O clock at 24 MHz
 - One Ref. clock at 14.318 MHz
- Innovative SmartLatch™ technology
 - Latches Select inputs only when PLLs are locked, ensuring proper input levels are latched
 - Power-up stabilization time = 2 ms on all CPU and PCI clocks, which meets Intel Pentium and Pentium Pro power-up requirements
- Low CPU clock jitter ≤ 200 ps cycle-to-cycle
- · Low skew outputs
 - —≤ 250 ps between CPU clocks
 - —≤ 250 ps between PCI clocks
 - 1ns-4ns skew between CPU and PCI clocks (in synchronous mode) for compatibility with Intel 82430VX and 82430HX chipsets, as well as Via and SiS chipsets

- · Improved output drivers are designed for low EMI
- · Test mode support
- · 3.3V operation, 5V tolerant inputs
- · Space saving and low cost 28-pin SOIC package

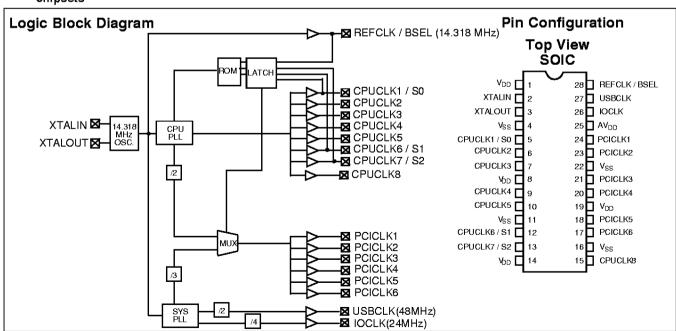
Functional Description

The CY2961 is a Clock Synthesizer/Driver chip for Pentium or Cyrix-based motherboards using Synchronous DRAM (SDRAM).

The CY2961 features four dual purpose I/O pins which provide extra CPU clocks, and enable the part to be packaged in a low-cost 28-pin SOIC package. These four pins feature innovative SmartLatch technology, which latches the select inputs only when all PLLs are locked, ensuring proper operation. Additionally, the device meets the Pentium and Pentium Pro power-up stabilization specifications, which require that CPU and PCI clocks be stable within 2 ms after power-up.

The CY2961 clock outputs are designed for low EMI emissions. Controlled rise and fall times, unique output driver circuits, and innovative circuit layout techniques enable the CY2961 to have lower EMI than clock devices from other manufacturers. Please refer to the application note "Layout and Termination Techniques for Cypress Clock Generators" for more information on recommended system layout techniques.

The CY2961 accepts a 14.318 MHz reference crystal or clock as its input and runs off a 3.3V supply.



SmartLatch is a trademark of Cypress Semiconductor Corporation. Intel and Pentium are registered trademarks of Intel Corporation. Cyrix is a registered trademark of Cyrix Corporation.



Pin Summary

Name	Pin	Description		
V _{DD}	1	Voltage supply		
XTALIN ^[1, 2]	2	Reference crystal input		
XTALOUT ^[1]	3	Reference crystal feedback		
V _{SS}	4	Ground		
CPUCLK1 / S0	5	CPU clock output / CPU clock select input, bit 0		
CPUCLK2	6	CPU clock output		
CPUCLK3	7	CPU clock output		
V _{DD}	8	Voltage supply		
CPUCLK4	9	CPU clock output		
CPUCLK5	10	CPU clock output		
V _{SS}	11	Ground		
CPUCLK6 / S1	12	CPU clock output / CPU clock select input, bit 1		
CPUCLK7 / S2	13	CPU clock output / CPU clock select input, bit 2		
V _{DD}	14	Voltage supply		
CPUCLK8	15	CPU clock output		
V _{SS}	16	Ground		
PCICLK6	17	PCI clock output		
PCICLK5	18	PCI clock output		
V _{DD}	19	Voltage Supply		
PCICLK4	20	PCI clock output		
PCICLK3	21	PCI clock output		
V _{SS}	22	Ground		
PCICLK2	23	PCI clock output		
PCICLK1	24	PCI clock output		
AV _{DD}	25	Analog voltage supply		
IOCLK	26	I/O clock output, 24 MHz		
USBCLK	27	USB clock output, 48 MHz		
REFCLK / BSEL	28	Reference clock output (14.318 MHz) for ISA slots (drives C _{LOAD} = 45 pF) Bus Select input. Selects Asynchronous or Synchronous PCI clocks. See Function Table.		

Notes:

For best accuracy, use a parallel-resonant crystal, C_{LOAD} = 12 pF.
 TCLK is a test clock on the XTALIN input during test mode.



Function Table (-1 Option)

S 2	S 1	So	XTALIN	CPUCLK[1-8]	PCICLK[1-6] BSEL = 1	PCICLK[1-6] BSEL = 0	REFCLK	USBCLK	IOCLK
0	0	0	14.318 MHz	50.0 MHz	25.0 MHz	32.0 MHz	14.318 MHz	48 MHz	24 MHz
0	0	1	14.318 MHz	60.0 MHz	30.0 MHz	32.0 MHz	14.318 MHz	48 MHz	24 MHz
0	1	0	14.318 MHz	66.67 MHz	33.33 MHz	32.0 MHz	14.318 MHz	48 MHz	24 MHz
0	1	1	TCLK ^[3]	TCLK/2 ^[4]	TCLK/4	TCLK/4	TCLK	TCLK/2	TCLK/4
1	0	0	14.318 MHz	55.0 MHz	27.5 MHz	32 MHz	14.318 MHz	48 MHz	24 MHz
1	0	1	14.318 MHz	75.0 MHz	37.5 MHz	32 MHz	14.318 MHz	48 MHz	24 MHz
1	1	0	14.318 MHz	83.3 MHz	41.7 MHz	32 MHz	14.318 MHz	48 MHz	24 MHz
1	1	1	14.318 MHz	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z

Function Table (-2 Option)

S 2	S 1	So	XTALIN	CPUCLK[1-8]	PCICLK[1-6] BSEL = 1	PCICLK[1-6] BSEL = 0	REFCLK	USBCLK	IOCLK
0	0	0	14.318 MHz	50.0 MHz	25.0 MHz	32.0 MHz	14.318 MHz	48 MHz	24 MHz
0	0	1	14.318 MHz	60.0 MHz	30.0 MHz	32.0 MHz	14.318 MHz	48 MHz	24 MHz
0	1	0	14.318 MHz	66.67 MHz	33.33 MHz	32.0 MHz	14.318 MHz	48 MHz	24 MHz
0	1	1	TCLK[3]	TCLK/2 ^[4]	TCLK/4	TCLK/4	TCLK	TCLK/2	TCLK/4
1	0	0	14.318 MHz	55.5 MHz	27.75 MHz	32 MHz	14.318 MHz	48 MHz	24 MHz
1	0	1	14.318 MHz	75.0 MHz	37.5 MHz	32 MHz	14.318 MHz	48 MHz	24 MHz
1	1	0	14.318 MHz	72.0 MHz	36.0 MHz	32 MHz	14.318 MHz	48 MHz	24 MHz
1	1	1	14.318 MHz	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z

Actual Clock Frequency Values

Clock Output	Target Frequency (MHz)	Actual Frequency (MHz)	PPM
CPUCLK	83.3	83.308	-331
CPUCLK	75.0	75.0	0
CPUCLK	72.0	72.0	0
CPUCLK	66.67	66.56	-1597
CPUCLK	60.0	60.0	0
CPUCLK	55.56	55.537	+331
CPUCLK	55.0	54.98	-331
CPUCLK	50.0	49.93	-1399
PCICLK ^[5]	32.0	32.005	167
USBCLK ^[6]	48.0	48.008	167
IOCLK	24.0	24.004	167

Notes:

TCLK is supplied on XTALIN pin.
 Bidirectional CPUCLK I/O pins are High-Z in Test mode
 If BSEL = 1, the PPM on PCICLK will be the same as on CPUCLK.
 Meets Intel USB clock requirements.



CPU and PCI Clock Driver Strengths

- Matched impedances on both rising and falling edges on the output drivers
- Output impedance: 25Ω (typical) measured at 1.5V.

Maximum Ratings

(Above which the useful life may be impaired. For user guide-lines, not tested.)

Supply Voltage	0.5 to +7.0 V
Input Voltage	–0.5V to V _{DD} +0.5
Storage Temperature (Non-Condensing)	65°C to +150°C
Max. Soldering Temperature (10 sec)	+260°C
Junction Temperature	+150°C
Package Power Dissipation	1W
Static Discharge Voltage(per MIL-STD-883, Method 3015)	>2000V

Operating Conditions[7]

Parameter	Description	Min.	Max.	Unit
V_{DD}	Supply Voltage	3.135	3.6	٧
T _A	Operating Temperature, Ambient	0	70	°C
CL	Max. Capacitive Load on CPUCLK PCICLK USBCLK IOCLK REFCLK		30 30 20 20 45	pF
f _(REF)	Reference Frequency, Oscillator Nominal Value	14.318	14.318	MHz

Electrical Characteristics $V_{DD} = 3.135V$ to 3.6V, $T_A = 0$ °C to +70°C

Parameter	Description		Test Conditions	s	Min.	Max.	Unit
V _{IH}	High-level Input Voltage	Except Crystal Inp	2.0		V		
V _{IL}	Low-level Input Voltage	Except Crystal Inp	outs			0.8	V
V _{OH}	High-level Output Voltage	$V_{DD} = V_{DD} Min.$	I _{OH} = 12 mA	CPUCLK	2.4		V
			I _{OH} = 12 mA	PCICLK	1		
			I _{OH} = 8 mA	USBCLK	1		
			I _{OH} = 8 mA	IOCLK	1		
			I _{OH} = 12 mA	REFCLK	1		
V _{OL}	Low-level Output Voltage	$V_{DD} = V_{DD} Min.$	I _{OL} = 12 mA	CPUCLK		0.4	V
			I _{OL} = 12 mA	PCICLK	1		
			I _{OL} = 8 mA	USBCLK	1		
			I _{OL} = 8 mA	IOCLK	1		
			I _{OL} = 12 mA	REFCLK	1		
l _{IH}	Input High Current	$V_{IH} = V_{DD}$		5	μА		
I _{IL}	Input Low Current	$V_{IL} = 0V$		5	μΑ		
loz	Output Leakage Current	Three-state	-10	+10	μΑ		
I _{DD}	Power Supply Current	$V_{DD} = 3.6V, V_{IN} =$		140	mA		
I _{DD}	Power Supply Current	$V_{DD} = 3.6V, V_{IN} =$	0 or V _{DD} , Unload	ed Outputs		95	mA

Note:

^{7.} Electrical parameters are guaranteed with these operating conditions.



Switching Characteristics^[8]

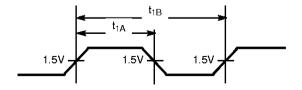
Parameter	Output	Description	Test Conditions	Min.	Тур.	Max.	Unit
t ₁	All	Output Duty Cycle ^[9]	$t_1 = t_{1A} \div t_{1B}$	45	50	55	%
t _{1C}	CPUCLK	CPU Clock HIGH Time	Measured at 2.4V, 66.67 MHz	5.0			ns
t _{1C}	PCICLK	PCI Clock HIGH Time ^[10]	Measured at 2.4V, 33.33 MHz	12.0			ns
t _{1D}	CPUCLK	CPU Clock LOW Time	Measured at 0.4V, 66.67 MHz	5.0			ns
t _{1D}	PCICLK	PCI Clock LOW Time ^[10]	Measured at 0.4V, 33.33 MHz	12.0			ns
t ₂	CPUCLK	CPU Clock Rising and Falling Edge Rate	Measured between 0.8V and 2.0V	1.0		4.0	V/ns
t ₂	PCICLK	PCI Clock Rising and Falling Edge Rate	Measured between 0.8V and 2.0V	1.0		4.0	V/ns
t ₂	REFCLK	Reference Clock Rising and Falling Edge Rate	Measured between 0.8V and 2.0V	0.5			V/ns
t ₃	CPUCLK	CPU Clock Rise Time	Measured between 0.8V and 2.0V	0.3		1.2	ns
t ₃	USBCLK, IOCLK	USB Clock and I/O Clock Rise Time	Measured between 0.8V and 2.0V			1.2	ns
t ₄	CPUCLK	CPU Clock Fall Time	Measured between 2.0V and 0.8V	0.3		1.2	ns
t ₄	USBCLK, IOCLK	USB Clock and I/O Clock Fall Time	Measured between 2.0V and 0.8V			1.2	ns
t ₅	CPUCLK	CPU-CPU Clock Skew	Measured at 1.5V		100	250	ps
t ₆	PCICLK	PCI-PCI Clock Skew	Measured at 1.5V		100	250	ps
t ₇	CPUCLK, PCICLK	CPU-PCI Clock Skew ^[11]	Measured at 1.5V	1	2.5	4	ns
t ₈	CPUCLK	Cycle-Cycle Clock Jitter	CPU Clock jitter			200	ps
t ₈	PCICLK	Cycle-Cycle Clock Jitter	PCI Clock jitter			500	ps
tg	CPUCLK	Power-up Time	CPU clock stabilization from power-up			2	ms
t ₁₀	PCICLK	Power-up Time	PCI clock stabilization from power-up			2	ms
t ₁₁	CPUCLK	Frequency Slew Rate	Rate of change of frequency	0.1	2	10	MHz/ ms

Notes:

- All parameters specified with loaded outputs.
 Duty cycle is measured at 1.5V.
 A LOW and HIGH time of 12 ns corresponds to a PCICLK frequency of 33.33 MHz. For PCICLK frequencies of 30 MHz and 25 MHz, the LOW and HIGH times are each respectively 13.33 ns and 16 ns.
 Synchronous PCI mode only.

Switching Waveforms

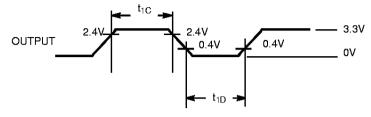
Duty Cycle Timing



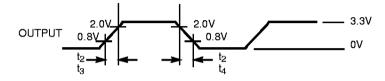


Switching Waveforms (continued)

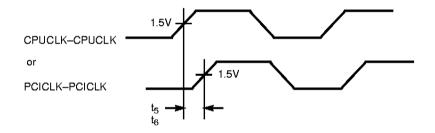
CPUCLK/PCICLK HIGH/LOW Times



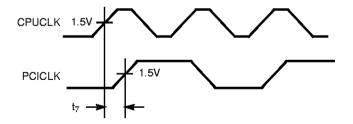
All Outputs Rise/Fall Time



Clock Skew



CPU-PCI Clock Skew





Application Information

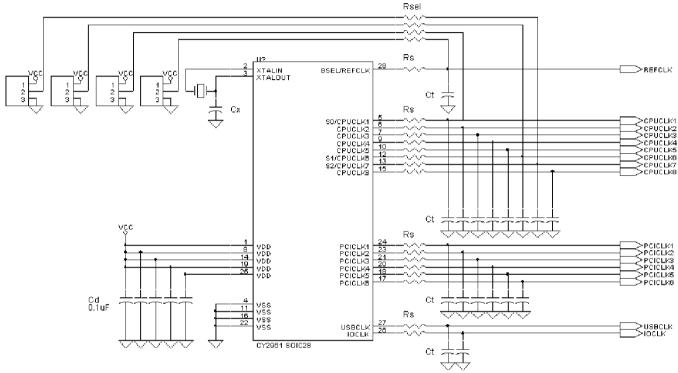
The CY2961 features SmartLatch technology which latches the select inputs only when both PLLs are locked. This eliminates spurious latching caused by noise on the power supply pins during ramp-up.

To use the SmartLatch feature, the four select inputs (S2, S1, S0, and BSEL) must be tied to either V_{CC} or V_{SS} through 10K Ω resistors. This will enable the user to select the appropriate CPUCLK and PCICLK frequencies from the Function Table.

Clock traces must be terminated with either series or parallel termination, as they are normally done.

The Application Circuit is shown below.

Application Circuit



Cd = DECOUPLING CAPACITORS

Ct = OPTIONAL EMI-REDUCING CAPACITORS

CX = OPTIONAL LOAD MATCHING CAPACITOR

Rf = FILTERING RESISTOR

Rs = SERIES TERMINATING RESISTORS

Rsel = STRAPPING RESISTERS (INSTALLED TO PULL EITHER UP OR DOWN)
TYPICAL VALUE = 10K OHMS

Summary

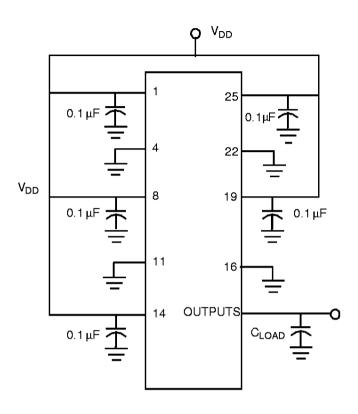
- A parallel-resonant crystal should be used as the reference to the clock generator. The operating frequency and C_{LOAD} of
 this crystal should be as specified in the data sheet. Optional trimming capacitors may be needed if a crystal with a different
 C_{LOAD} is used. Footprints must be laid out for flexibility.
- Surface mount, low-ESR, ceramic capacitors should be used for filtering. Typically, these capacitors have a value of 0.1 μF.
 In some cases, smaller value capacitors may be required.
- The value of the series terminating resistor satisfies the following equation, where R_{trace} is the loaded characteristic impedance
 of the trace, R_{out} is the output impedance of the clock generator (specified in the data sheet), and R_{series} is the series terminating
 resistor.

$$R_{\text{series}} \ge R_{\text{trace}} - R_{\text{out}}$$

- Footprints must be laid out for optional EMI-reducing capacitors, which should be placed as close to the terminating resistor as is physically possible. Typical values of these capacitors range from 4.7 pF to 22 pF.
- A Ferrite Bead may be used to isolate the Board V_{DD} from the clock generator V_{DD} island. Ensure that the Ferrite Bead offers greater than 50Ω impedance at the clock frequency, under loaded DC conditions. Please refer to the application note "Layout and Termination Techniques for Cypress Clock Generators" for more details.
- If a Ferrite Bead is used, a 10 μF– 22 μF tantalum bypass capacitor should be placed close to the Ferrite Bead. This capacitor prevents power supply droop during current surges.



Test Circuit



Note: All capacitors should be placed as close to each pin as possible.

Ordering Information

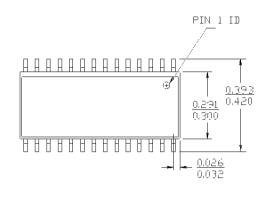
Ordering Code	Package Name	Package Type	Operating Range
CY2961SC-1	S21	28-Pin SOIC	Commercial
CY2961SC-2	S21	28-Pin SOIC	Commercial

Document #: 38-00531-B



Package Diagram

28-Lead (300-Mil) Molded SOIC S21



DIMENSIONS IN INCHES MIN. MAX. LEAD COPLANAPITY 0.004 MAX.

